
Guest editorial

IMAPS 2018

The International Microelectronics and Packaging Society (IMAPS) Poland Chapter was established in September 1982. In the beginning, it was the ISHM-Poland Chapter, and from 1997, it became the IMAPS-Poland Chapter.

The IMAPS is a non-profit making organization whose aim is to spread of knowledge relating to hybrid microelectronics; a key technology in the assembly and application of semiconductors, thin film circuits and printed circuit boards to form practical miniaturized electronic equipment. In 2008, the IMAPS joined with IEEE Components, Packaging and Manufacturing Technology (CPMT) Society, bringing into formation the IMAPS-CPMT organization.

The 42nd IMAPS Poland International Conference was held in Biały Dom Hotel near Gliwice and took place between 23 and 26 September 2018. This event was organized by the Silesian University of Technology. The scope of the Conference covered everything in electronics between the chip and the system. The conference was attended by 71 participants, including 14 guests from abroad. During the Conference, 15 invited lectures and 42 posters were presented. The conference was supported by six international

journals indexed in Journal Citation Report database and one journal indexed in Scopus.

This year, as in the previous year, two young scientists have been awarded winning the refund of the conference fee during the next IMAPS 2019 Poland Conference.

In the special issue of *Microelectronics International*, seven papers have been collected. All of them were subjected to the journal's regular reviewing procedure.

First, four papers by Swatowska *et al.*, Sobik *et al.*, Drabczyk *et al.* and Filipowski *et al.* are related to photovoltaics issues.

In the next paper, Firek *et al.* describe the influence of AlN etching process on MISFET structures.

Jasińska *et al.* deal with the influence of screen-printing parameters on path resolution on LTCC substrates.

In the last paper, Walter *et al.* report the development of the screen-printed electrodes for the detection of organophosphorus pesticides

I would like to thank all the authors for their scientific work and contributions that have led to the development and publication of this special issue of *Microelectronics International*. I hope that it will be of interest to readers of the journal and that it will help them to find novel solutions, contribute to the creation of new ideas and initiate many varied discussions about different technologies and problems related to microelectronics issues. I believe that this branch of science could be effectively developed in the future.

Agata Skwarek

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